



## Product Change Notification - ASER-17GSOU325

---

**Date:**

17 Jan 2020

**Product Category:**

Clock and Timing - Oscillators; Others

**Affected CPNs:****Notification subject:**

CCB 3960.001 and 3960.002 Initial Notice: Qualification of new bill of materials (BOM) for selected Micrel products available in 4L VDFN (3.2 x 2.5 x 0.9 mm) and 4L VDFN (2.5 x 2.0 x 0.9 mm) packages at NSEB assembly site.

**Notification text:****PCN Status:**

Initial notification.

**PCN Type:**

Manufacturing Change

**Microchip Parts Affected:**

Please open one of the icons found in the Affected CPNs section above.

NOTE: For your convenience Microchip includes identical files in two formats (.pdf and .xls).

**Description of Change:**

Qualification of new bill of materials (BOM) for selected Micrel products available in 4L VDFN (3.2 x 2.5 x 0.9 mm) and 4L VDFN (2.5 x 2.0 x 0.9 mm) packages at NSEB assembly site.

**Pre Change:**

Assembled at NSEB using A194 lead frame material, NEX-130CT die 1 attach material, 8200T die 2 attach material, G770HCD molding compound and Q3-6646 die coat.

**Post Change:**

Assembled at NSEB using A194 lead frame material, HR-5104 die 1 attach material, 2200D die 2 attach material, G700LTD molding compound, and JCR6109 die coat.

**Pre and Post Change Summary:**

	Pre Change	Post Change
<b>Assembly Site</b>	UTAC Thai Limited LTD. (NSEB)	UTAC Thai Limited LTD. (NSEB)
<b>Lead Frame Material</b>	A194	A194
<b>Bond Wire Material</b>	Au	Au
<b>Die 1 Attach Material</b>	NEX-130CT	HR-5104
<b>Die 2 Attach Material</b>	8200T	2200D
<b>Molding compound material</b>	G770HCD	G700LTD
<b>Die Coat</b>	Q3-6646	JCR6109

**Impacts to Data Sheet:**

None.



**Change Impact:**

None.

**Reason for Change:**

To improve manufacturability by qualifying new die attach material, molding compound and die coat.

**Change Implementation Status:**

In Progress

**Estimated Qualification Completion Date:**

March 2020

Note: Please be advised the qualification completion times may be extended because of unforeseen business conditions however implementation will not occur until after qualification has completed and a final PCN has been issued. The final PCN will include the qualification report and estimated first ship date. Also note that after the estimated first ship date guided in the final PCN customers may receive pre and post change parts.

**Time Table Summary:**

	January 2020					-->	March 2020				
Workweek	1	2	3	4	5		10	11	12	13	14
Initial PCN Issue Date		X									
Qual Report Availability										X	
Final PCN Issue Date										X	

**Method to Identify Change:**

Traceability code.

**Qualification Plan:**

Please open the attachments included with this PCN labeled as PCN\_#\_Qual\_Plan.

**Revision History:**

**January 07, 2020:** Issued initial notification.

**January 17, 2020:** Reissued initial notification to remove BQM information. The BQM will not be changing.

The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable products.

**Attachment(s):**

[PCN\\_ASER-17GSOU325\\_Qual Plan.pdf](#)

Please contact your local [Microchip sales office](#) with questions or concerns regarding this notification.

**Terms and Conditions:**



If you wish to [receive Microchip PCNs via email](#) please register for our PCN email service at our [PCN home page](#) select register then fill in the required fields. You will find instructions about registering for Microchips PCN email service in the [PCN FAQ](#) section.

If you wish to [change your PCN profile, including opt out](#), please go to the [PCN home page](#) select login and sign into your myMicrochip account. Select a profile option from the left navigation bar and make the applicable selections.